

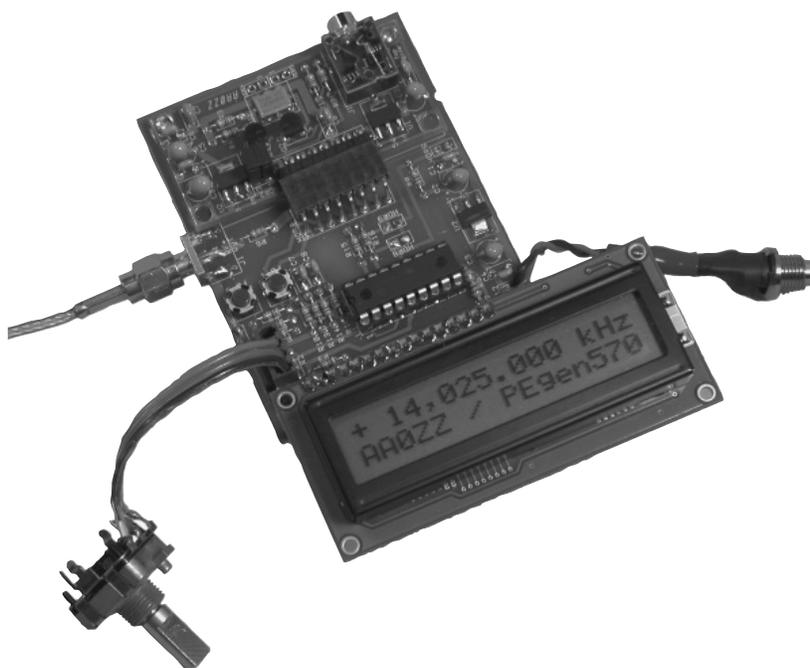
Programmable PLL (Si570) Local Oscillator for HF Receivers, Transmitters and Tranceivers

The Silicon Labs Si570 is a versatile programmable phase locked loop IC with many possible Amateur Radio applications. This PLL synthesizer is one good example.

A new product has recently been developed by Silicon Labs, the Si570 DSPLL[®] programmable frequency synthesizer, and it has great potential for use in many Amateur Radio applications. Here we will explore some possible uses. Phase locked loop technology has been in use for many years, but the ability to use variable software-supplied loop parameters in PLL technology to directly generate square waves with frequency resolutions of 1 Hz or better is now possible. The Si570 immediately puts the new technology into the sphere of uses that has recently been dominated by direct digital synthesis (DDS) products.

This AA0ZZ Si570 daughtercard uses the Silicon Labs Si570 (CMOS version) and, when controlled by a microcontroller, can generate RF signals in the continuous range of 10 to 157 MHz. (Other versions of the Si570 can go up to 1.4 GHz.) When the daughtercard is incorporated into a control board, the Si570 daughtercard can easily be used as the local oscillator of an Amateur Radio transceiver. Since many amateurs use divide-by-four mechanisms in quadrature sampling detectors (QSD) — also known as “Taylor” mixers — for their receivers and also in quadrature sampling exciters (QSE) for their transmitters, this Si570 daughtercard can provide the local oscillator signal for these receivers and transmitters on the 80 through 10 meter amateur bands.¹

¹Notes appear on page 16.



Si570 Operation

Figure 1 shows a block diagram of the Si570. The Si570 offers some significant advantages over the DDS parts that have been used by amateurs in applications in recent years. Two advantages are greatly reduced power consumption and the relatively clean output without DDS byproducts (spurs). The Si570 uses a combination of DSP processing and a PLL topology with frequency selection parameters set by the user via an PC serial communications link to

generate the desired output frequency.

Silicon Labs offers several versions of the Si570 with different output options and frequency limits. I used a CMOS version of the Si570 for this project. It has a 10.0 MHz default frequency and a 160 MHz maximum frequency. The internal crystal of the Si570 runs at a nominal 114.285 MHz. The crystal in any individual part will not oscillate at exactly this frequency, however. Since the crystal frequency is used in the frequency generation calculations for the Si570 input

parameter words, any deviation from nominal means that the Si570 generated frequency will not be accurate. Fortunately, Silicon Labs calibrates each individual part in the factory and saves the calibrated parameters in its nonvolatile memory to cause it to start up at the default frequency (in this case, 10.0 MHz). The software can retrieve these parameters from the nonvolatile memory and thus calculate the calibrated crystal frequency. This calibrated crystal frequency can then be used in subsequent calculations and the results will be much more accurate than they would be if the nominal crystal frequency was used for the calculations.

Si570 Functional Description

The spec sheet of the Si570 is a real challenge to interpret. The description given here will not substitute for a thorough reading of the spec sheet but it will get you started. (You can find the full details on the Silicon Labs website at www.silabs.com/SupportDocuments/TechnicalDocs/si570.pdf.)

Command data bytes are sent from the controller to the Si570 registers by way of the standard I²C serial communications protocol. (The I²C communications protocol is described later in the article.) The basic control registers are shown in Table 1.

Si570 Output Frequency Generation

The Si570 has a digitally-controlled oscillator (DCO), driven by a fixed-frequency crystal and PLL loop-control parameters. There are three frequency selection parameters that the software must set up for the Si570 to generate the desired output frequency. The basic frequency generation formula is:

$$F_{out} = (F_{xtal} \times RFREQ) / (HS_DIV \times N1)$$

where:

F_{xtal} is the fixed crystal frequency (114.285 MHz nominal) RFREQ is a 38 bit variable consisting of a 10 bit integer and a 28 bit fraction. HS_DIV can be 4, 5, 6, 7, 9 or 11. N1 can be 1 or any even integer between (and including) 2 and 128.

Additional parameter selection constraints are as follows. First, the DCO frequency specified in the numerator of this equation (F_{xtal} × RFREQ) must always be in the range of 4.85 GHz to 5.67 GHz. Since the F_{xtal} value is 114.285 MHz, the RFREQ range is 42.44 to 49.613. This DCO

range can be stretched to some extent, as evidenced by the default setup parameters set up in a sample Si570 with factory settings for 10 MHz (see the SetupFxtal routine later in the article).

The second constraint is to optimize for minimal power consumption. Many different combinations of RFREQ, N1 and HS_DIV that will produce a given output frequency are possible to use. The lowest value of N1, along with the highest value of HS_DIV results in the lowest power consumption.

Si570 Freeze DCO

When specifying the parameters for

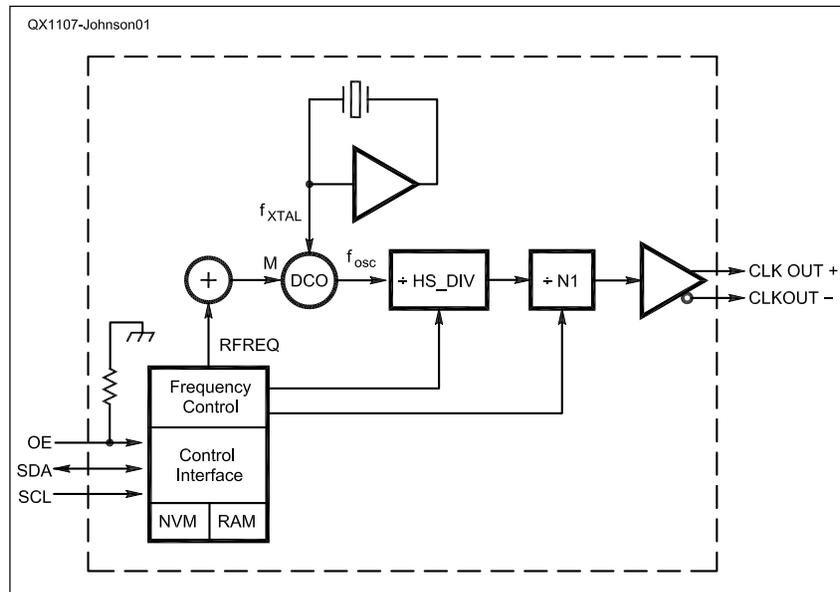


Figure 1 — Here is a simple block diagram illustrating the operation of the Silicon Labs Si570 programmable PLL IC.

Table 1
Si570 Control Registers

Register	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Si Reg 7	HS_DIV_Index [2:0]			(N1 - 1) [6:2]				
Si Reg 8	(N1 - 1) [1:0]		RFREQ (integer) [37:32]					
Si Reg 9	RFREQ (integer) [31:28]				RFREQ (fractional) [27:24]			
Si Reg 10	RFREQ (fractional) [23:16]							
Si Reg 11	RFREQ (fractional) [15:8]							
Si Reg 12	RFREQ (fractional) [7:0]							
Si Reg 135	RST_REG	New Freq	Freeze M					RECALL
Si Reg 137				Freeze DCO				

Figure 2 — This drawing illustrates the frequency range that does not require a DCO Freeze operation before changing frequency. A larger change will require a DCO Freeze operation first.

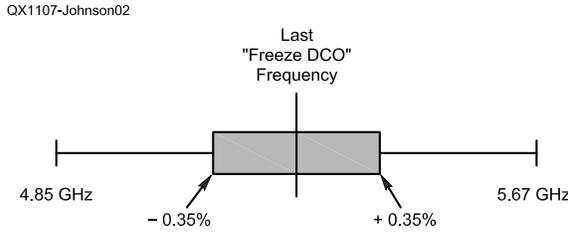
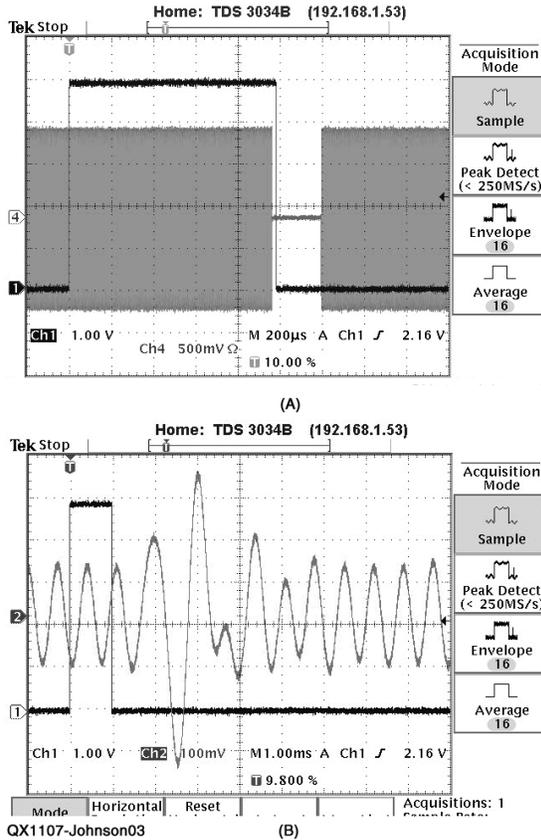


Figure 3 — Part A shows an oscilloscope display of the RF dropout following a DCO Freeze. Part B shows an oscilloscope display of the audio “pop” that follows a DCO Freeze.



changing the output frequency of the Si570, the current frequency must also be considered. Large frequency changes require the DCO to be stopped and restarted before it can jump to the new frequency while small changes do not. Freezing the DCO is done by setting the “Freeze DCO” bit (bit 4 in SiReg 137) before sending the normal frequency update registers (Registers 7 - 12) to the Si570. After the frequency update the “Freeze DCO” bit is cleared to unlock the DCO.

If the difference between the new frequency and the last freeze frequency is more than 3500 parts per million (0.35%) of the last freeze frequency, a DCO freeze is needed. Figure 2 shows the frequency range of the DCO oscillator (specified by $F_{xtal} \times RFREQ$) and the frequency range that can be covered without a freeze. If the output change is less than 0.35% from the last freeze frequency, the DCO frequency is the only value that needs to be changed for the frequency update.

Why not just do a freeze/unfreeze on every frequency update and skip the calculation to determine whether or not it is necessary? Because it can take a relatively long time (up to 10 ms) for the RF to “settle” on the new frequency and the RF output is stopped during this period. See Figure 3.

In this example, trace 1 is high during the freeze-update-unfreeze sequence (980 μ s) and trace 4 shows the RF dropout (220 μ s). The RF dropout that occurs when the Si570 is stopped and restarted at the new frequency after a DCO freeze causes an audible pop in a receiver. See Figure 3B for an oscilloscope screen shot of the audio pop. Channel 1 is high during the DCO freeze and Channel 2 is the audio. Small frequency changes without a DCO freeze do not cause the pop sound.

Freeze M

It takes a measureable amount of time

Figure 4 — Here is an oscilloscope display of the Si570 RF output at 14.025 MHz.

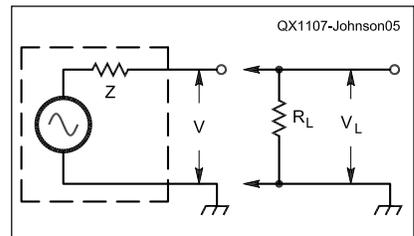
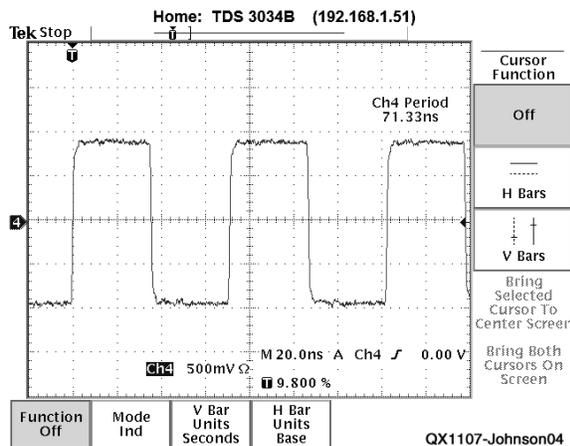


Figure 5 — A basic test circuit to measure the Si570 output impedance.

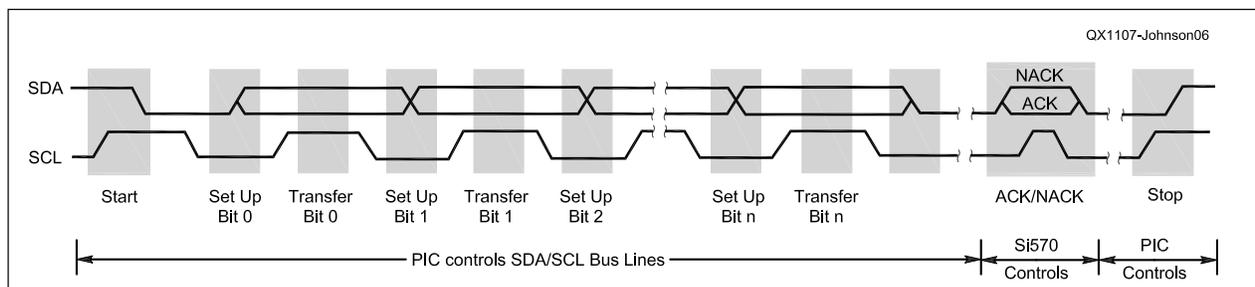


Figure 6 — The I2C data transfer timing diagram.

to send the six frequency configuration (RFREQ and loop parameter) bytes to the Si570 registers via the I²C communications link. (It takes 120 μs if sent at the maximum I²C communications link speed of 400 kHz and 667 μs in the PEGen570 application with an I²C rate of 72 kHz.) As the six bytes are being sent, one bit at a time, the Si570 is using the registers to spray RF signals at undesired frequencies. Granted, the time is short and the RF signal is often not being transmitted while the frequency is being changed so this random RF would not be going far, but it could be a significant problem for FSK (where the transmitter stays on as it shifts between the MARK and SPACE frequencies) or for other digital modes.

The FREEZE M feature solves this problem. The FREEZE M bit (Bit 5 in configuration byte 135) is designed to be set just before the frequency update is done and cleared after all six bytes are transferred. Note that this is different from the FREEZE DCO functionality, which is required when the frequency changes by more than 0.35% from the last freeze. The FREEZE DCO function will continue to be used; however, this is for the small frequency updates in which a FREEZE DCO is not needed. This new FREEZE M functionality causes the frequency update in the Si570 to be frozen until the FREEZE M bit is cleared. By then, all of the new frequency bytes are ready to be used and the Si570 jumps directly to that frequency.

Si570 RF Output and Output Impedance

The Si570 RF output is close to a square wave. An example of a CMOS Si570 running at 14.025 MHz into a 50 Ω load is shown in Figure 4. Here the output RF signal level is about 1.7 V p-p.

Calculations were done to determine the output impedance of the Si570. The basic test circuit is shown in Figure 5.

First the output voltage, V, is measured with no load resistor. This is the same as the source voltage, since there is no current through Z at this time. Then a shunt resistor with known resistance is placed across

the output and the voltage, V_L, is measured. Using the following equations, the output impedance is calculated.

$$I = V / (Z + R_L)$$

$$V_L = R_L \times I$$

$$V_L = R_L \times V / (Z + R_L)$$

$$Z = R_L \times ((V - V_L) / V_L)$$

An 18 Ω load resistor in the test circuit produced the following results:

$$V = 3.8 \text{ V}$$

$$V_L = 3.4 \text{ V}$$

$$Z = 18 \times ((2 - 1.2) / 1.2) = 12 \Omega$$

This means that a 38 Ω series resistor could be used to match the Si570 RF output to a 50 Ω load.

I²C Communications

The control interface to the Si570 is an I²C-compatible 2-wire bus for bidirectional communication. The I²C address for an Si570 is always 55 (hex). Since the slave address for I²C is a 7 bit field, the most significant bit is truncated and the direction bit (0 for a Write operation) is placed in the least significant bit of this byte. For a Write com-

mand to the Si570, the bit order is as shown in Table 2. The operation and timing of the two I²C signals on the bidirectional bus is illustrated in Figure 6.

When the source device and the destination device are communicating via the bidirectional I²C protocol, and they are operating with different voltage levels, hardware circuitry is necessary to translate the voltages. Many different schemes have been devised but a very simple and effective method, without the need for direction control signals, is described in the I²C Bus specification. With a single source (a PIC microcontroller) and a single destination (an Si570) the level shifting mechanism is as shown in Figure 7.

The level shifter consists of one discrete N-channel enhancement MOSFET for the serial data SDA bus line and one for the serial clock SCL bus line. The MOSFET gates are connected directly to the lowest supply voltage. The sources of the two MOSFETs are connected to the SDA and SCL bus lines on the 3.3 V device and the MOSFET drains are connected to the SDA and SCL bus lines

Table 2
The I²C bit order.

Start	Slave Adr + Dir	Ack	Data	Ack	Data	Ack	Stop
	1010101 0		xxxxxxx		xxxxxxx		

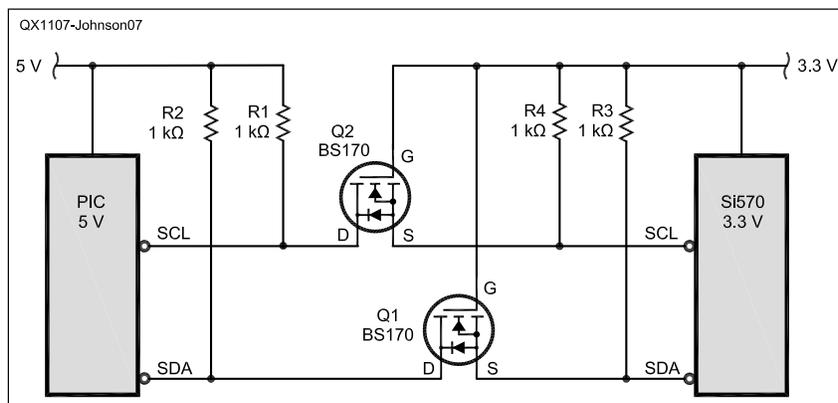


Figure 7 — This circuit shows an I²C level shifter.

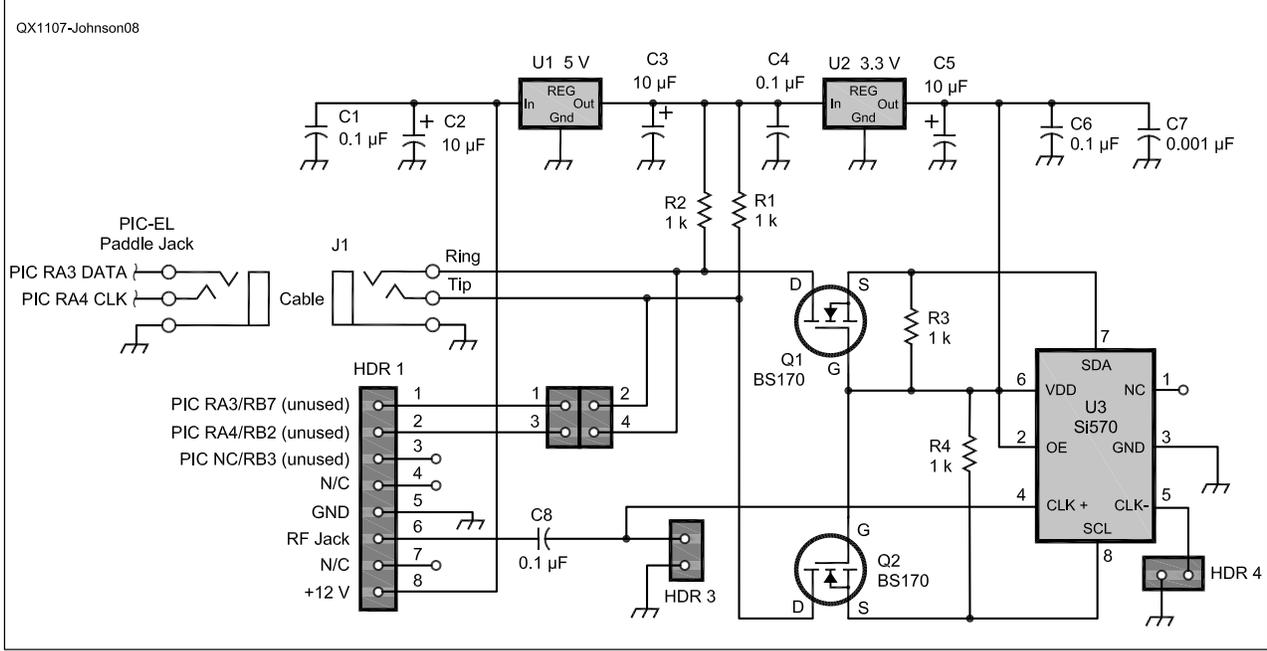


Figure 8 — The Si570 daughtercard schematic diagram.

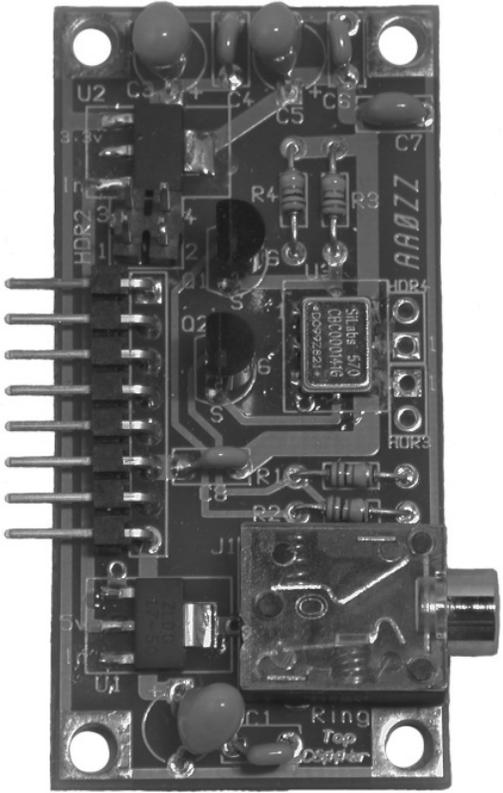


Figure 9 — This photo shows the Si570 daughtercard.

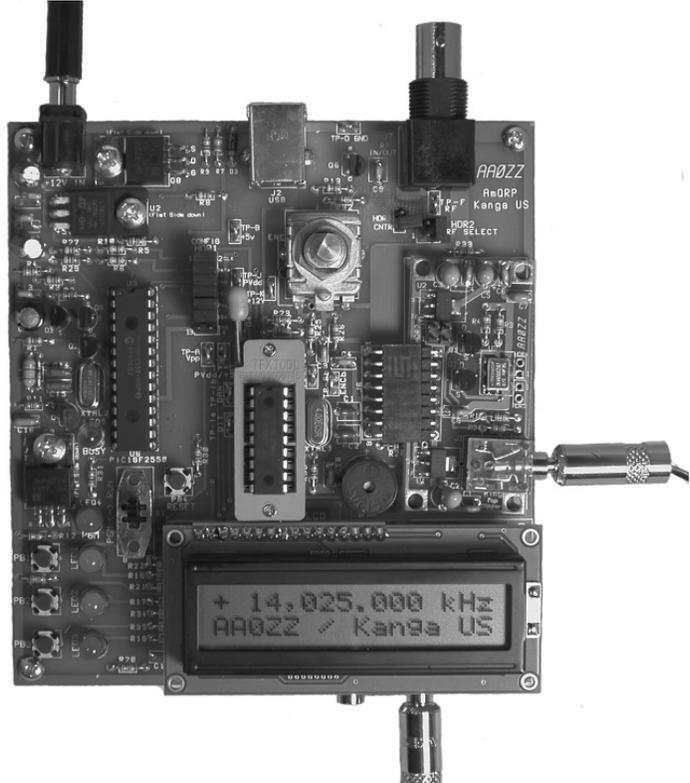


Figure 10 — Here, the Si570 daughtercard is plugged into the PIC-EL III board.

on the 5 V device. Each of these BS170 MOSFETs has an internal diode between the drain and source.

When neither device is pulling down a bus line (either SDA or SCL), the bus lines on the 3.3 V side are pulled up by the pull-up resistors R3 and R4 to 3.3 V. Since the gate and the source voltages of both MOSFETs are at 3.3 V, the V_{gs} voltages are below the turn-on threshold voltages so neither MOSFET is conducting. This allows the bus lines at the 5 V side to be pulled up by the pull-up resistors R1 and R2 to 5 V. The bus lines of both sides are HIGH but at different voltage levels.

When the 3.3 V device pulls down a bus line (SDA or SCL) to a LOW level, the source of the MOSFET also becomes LOW

while the gate stays at 3.3 V. As V_{gs} rises above the threshold, the MOSFET starts to conduct. The bus line on the 5 V side is also pulled down to a LOW level by the 3.3 V device via the conducting MOSFET. Both sides of the bus lines are LOW and at the same voltage level.

When the 5 V device pulls down a bus line (SDA or SCL) to a LOW level, the source of the MOSFET is also pulled to a LOW level via the drain-source diode internal to the MOSFET. As the source is pulled down, V_{gs} passes the turn-on threshold and the MOSFET starts to conduct. The bus line of the 3.3 V side is then further pulled down to a LOW level of the 5 V side via the conducting MOSFET. Both sides of the bus lines are LOW and at the same voltage level.

Si570 Daughtercard

The daughtercard schematic is shown in Figure 8. It has two voltage regulators. One converts 12 V to 5 V and the other converts 5 V to 3.3 V. Why not just bring a 5 V line from the PIC-EL to the daughtercard and avoid the 12 to 5 V regulator? Two voltage regulators are used because the PIC-EL daughtercard connector was designed to deliver 12 V for a DDS-30/60 daughtercard from the American QRP Club (www.amqrp.org), and the goal of this project was to use the existing PIC-EL circuitry without making hardware modifications.

Other versions of the Si570 have higher frequency limits but with reduced amplitude output. The spec sheet for the CMOS version

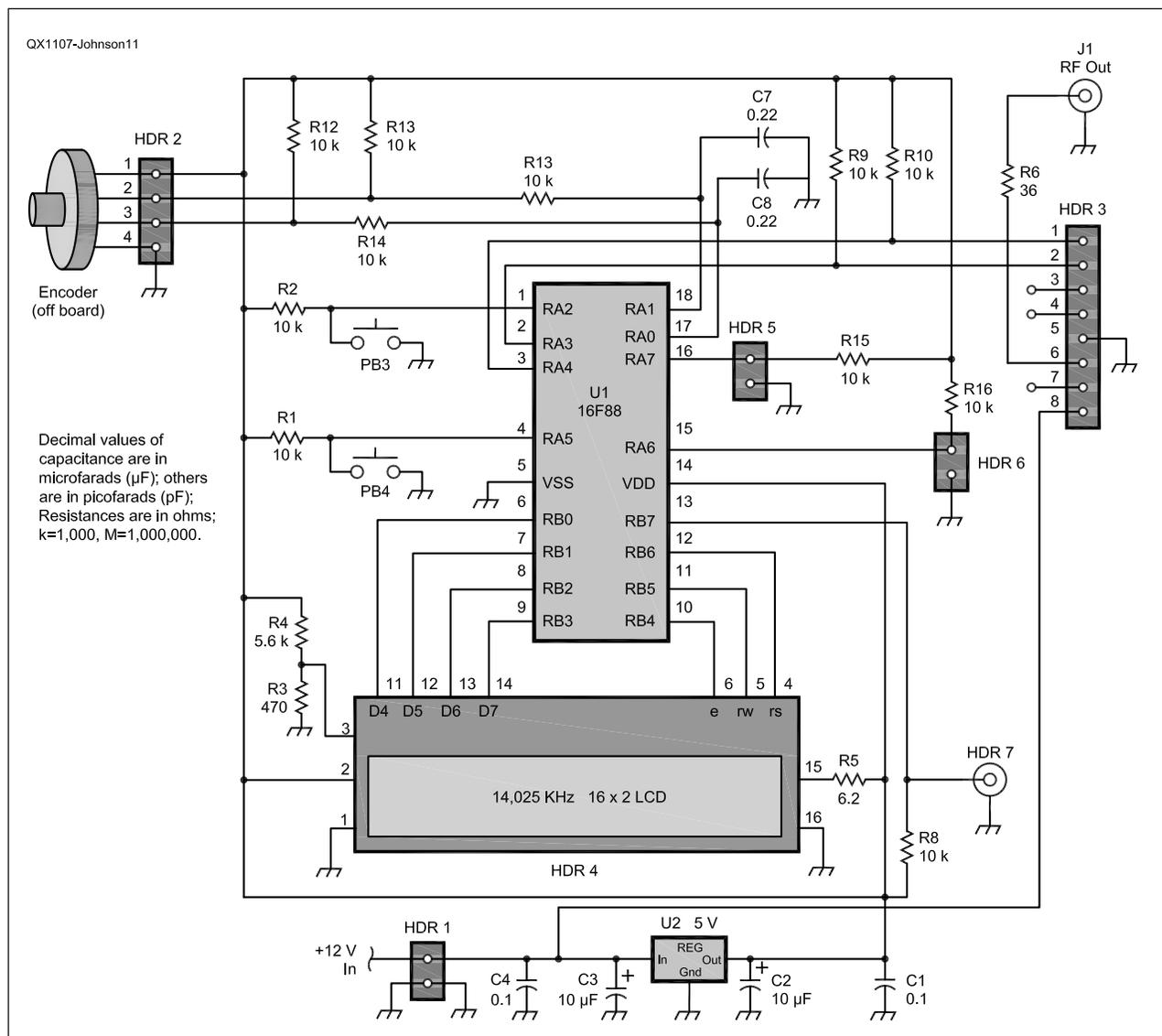


Figure 11 — This circuit is the Si570 control board schematic diagram.

says it operates between 10 and 160 MHz, but some users report it can be used between 3.5 and 240 MHz.

The daughtercard can be used in many different platforms. I will describe a couple of examples.

Daughtercard with PIC-EL

One platform for the Si570 daughtercard (Figure 9) is the AA0ZZ PIC-EL board (Figure 10). The PIC-EL board provides a very convenient platform for experimenting with the software to operate the Si570. I described the PIC-EL board in several *QST* articles.²

The Si570 daughtercard was designed to fit into an 8-pin socket on the PIC-EL board that was originally designed to accommodate an AmQRP DDS-30 or DDS-60 daughtercard. The DDS daughtercard operates with three control lines. The Si570 daughtercard is simpler in that it operates with two communications lines. The communications scheme used by the Si570 is I²C and that means the lines are both bidirectional. This presents a problem for the PIC-EL, since two of the three PIC lines that go to the daughtercard interface are also shared by the LCD and the other line is shared with the programmer. This sharing of pins prevents two-way communications via I²C with these lines. The workaround is to use an external cable to connect the daughtercard to the PIC-EL's paddle jack. The paddle jack connects to different PIC pins and these pins are only shared with PIC-EL Pushbuttons 2 and 3. These two pushbuttons cannot be used when operating the Si570 daughtercard but otherwise the lines work well for I²C communications.

The header (HDR2) on the daughtercard is a 2x2 connector block that is not used when the daughtercard is used in a PIC-EL with the external cable.

Daughtercard with Control Board

The Control Board schematic is shown in Figure 11.

When the daughtercard is used with a dedicated control board instead of a PIC-EL, then header HDR2, the 2x2 connector block, is put into use and the external cable from the stereo jack on the daughtercard to the driver platform is not needed. Two jumpers are installed in this header block (1 to 4 and 2 to 3) to route the I²C communications through the 8-pin interface connector.

The current required by the Si570 daughtercard alone is about 100 mA and the total current required by the daughtercard and the Control Board with LCD active is about 160 mA.

PEgen570 Software Application

The sample application software for the AA0ZZ Si570 daughtercard is called

PEgen570. It runs on a simple, inexpensive 16F88 PIC in the PIC-EL board. There are several reasons why the 16F88 was selected for this application instead of the PIC-EL standard 16F628A:

1) Compared to the 16F628A, the 16F88 has twice as much FLASH memory (for program instructions), 50% more data memory (for variable storage and tables) and twice as much EEPROM memory (non-volatile storage).

2) The 16F88 has an 8 MHz internal oscillator while the 16F628A has a 4 MHz internal oscillator. The extra speed is helpful.

Obviously, the user interface in the PEgen570 app is much simplified from the user interface in my IQPro DDS VFO but the application was simplified such that it could be developed and debugged on the PIC-EL board.³

Figure 12 shows an oscilloscope snapshot of the start of an I²C communication sequence in which the control board is sending a frequency update to the daughtercard. The I²C communications sequence begins with the falling edge of the SDA line (Channel 2) while the SCL line (Channel 1) is high. The next bits show the beginning of the 55 (hex) device address (lower 7 bits) as described in the I²C Communications section. The clock rate in this implementation is 72 kHz. Since the Si570 can handle speeds up to 400 kHz, this rate is well below the limit.

Frequency Selection Method

The methods for selecting N1, HS_DIV and calculating RFREQ for every frequency update are many. They can also be very time consuming, so optimization is especially important for a small microcontroller. For this reason, the following scheme was developed.

1) Create a list of pairings of all valid N1

and HS_DIV values. Calculate the frequency ranges that can be reached with each of these pairings. The total set of ranges must cover the intended operational range (10 MHz to 157 MHz). Since there are 65 valid N1 values and 6 valid HS_DIV values, there are 390 valid pairings, so there are 390 valid frequency ranges in this working table.

2) Examine the working set of pre-calculated frequency ranges for the N1 and HS_DIV pairings and select the minimum number of frequency ranges (bands) that can span the intended operational range of 10 to 157 MHz without gaps while starting and ending on MHz boundaries. Look for the bands with the widest frequency spans while also looking for the lowest N1 values and highest HS_DIV values. The total number of bands is limited by the size of a microcontroller memory bank (96 bytes) and each band entry requires 4 bytes, so 24 bands are possible.

3) Create a table that contains entries for the lowest frequency of each of the 24 bands.

4) Create a table of 1 byte entries for the selected bands, with each entry being constructed by multiplying the selected N1 by the HS_DIV value and then dividing the product by 2. If the N1 and HS_DIV pairings selected in Step 2 do not fit into 1 byte after they are multiplied and divided by 2, then rework the band selection tables. This may force the selection of some non-optimal N1 and HS_DIV pairings. It also limits the total operational range.

Note that no significant figures are lost in dividing the N1 and HS_DIV product by 2, since each valid N1 is an even number (or 1). The RFREQ calculations will take into account the fact that this division by 2 has taken place.

5) Construct the table, which contains entries combining Fxtal with N1 and HS_

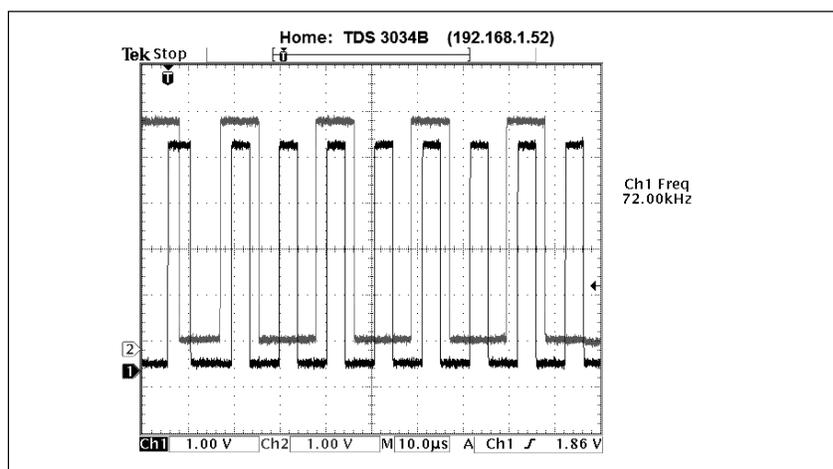


Figure 12 — This oscilloscope display shows the I²C communications, with SDA/SDC signals in the PEgen570 software application.

DIV for the corresponding frequency bands. Each entry will be $F_{xtal} / (N1 \times HS_DIV)$.

6) To calculate RFREQ for a given frequency, retrieve the appropriate table entry containing $F_{xtal} / (N1 \times HS_DIV)$ and divide the desired output frequency by this value. The result of this division must be a 10 bit integer and a 28 bit fraction.

7) Position N1, HS_DIV and RFREQ in the command packet to be sent via I²C to the Si570 control registers. To be exact, store (N1 – 1) instead of N1 and store the 3 bit

index corresponding to the selected HS_DIV value.

This scheme provides a relatively quick Si570 frequency update with some table look-ups and a single division. This single mathematical operation is not a simple one, however, since it divides a 40 bit integer value by a 32 bit integer value and results in a 10 bit integer and a 28 bit fraction positioned such that the five bytes can be directly loaded into the Si570 registers.

DCO Freeze Handling

Earlier in the article, I described the Si570 requirement for a DCO freeze when updating the frequency, if the frequency has moved by more than 3500 ppm (0.35%) from the last freeze frequency.

The software keeps track of the frequency at which the last freeze operation was done. If the difference between the new frequency and the last freeze frequency is more than 0.35% of the last freeze frequency, the freeze

Table 3
RFREQ in Si570 Registers

Register	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Hex
Si Reg 7	X	X	X	X	X	X	X	X	0xXX
Si Reg 8	X	X	0	0	0	0	1	0	0x02
Si Reg 9	1	1	0	1	1	1	1	0	0xDE
Si Reg 10	0	1	0	1	1	0	1	0	0x5A
Si Reg 11	1	0	0	0	1	1	0	1	0x85
Si Reg 12	0	1	0	1	0	1	0	0	0x55
SiReg135									
SiReg137									

HS_DIV_Index [2:0]
(N1 – 1) [6:0]
RFREQ-integer [37:28]
RFREQ-fractional [27:0]

Table 4
RFREQ, HSDIV and N1 in Si570 Registers

Register	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Hex
Si Reg 7	1	1	1	0	1	0	0	0	0xE8
Si Reg 8	0	1	0	0	0	0	1	0	0x42
Si Reg 9	1	1	0	1	1	1	1	0	0xDE
Si Reg 10	0	1	0	1	1	0	1	0	0x5A
Si Reg 11	1	0	0	0	1	1	0	1	0x85
Si Reg 12	0	1	0	1	0	1	0	0	0x55
SiReg135									
SiReg137									

HS_DIV_Index [2:0]
(N1 – 1) [6:0]
RFREQ-integer [37:28]
RFREQ-fractional [27:0]

Table 5
RFREQ Extracted From Nonvolatile Memory

Register	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Hex
Si Reg 7	0	1	0	1	0	0	1	1	0x53
Si Reg 8	1	1	0	0	0	0	1	0	0xC2
Si Reg 9	1	0	1	0	0	0	0	0	0xA0
Si Reg 10	0	1	0	1	0	0	0	0	0x50
Si Reg 11	1	1	1	0	1	0	0	1	0xE9
Si Reg 12	1	1	1	1	1	1	0	1	0xFD
SiReg135									
SiReg137									

HS_DIV_Index [2:0]
(N1 – 1) [6:0]
RFREQ-integer [37:28]
RFREQ-fractional [27:0]

and unfreeze operations are done along with the frequency update. Rather than doing another large division operation, the actual calculation is performed in a simplified manner by determining whether or not the new DCO frequency ($F_{xtal} \times RFREQ$) has moved by more than 0.35%. Since F_{xtal} is a constant, the worst case is found by taking the lower limit of the integer portion of the $RFREQ$ (42) and multiplying by 0.35%.

$$42 \times 0.35\% = 0.147$$

Then, if the software determines the new $RFREQ$ is changed by more than the constant 0.147 from the last freeze, a new freeze is done.

Major Subroutines of PEGen570

The frequency selection scheme that is used in PEGen570 was described earlier. This routine is called when a frequency update is needed. The job of this routine is to calculate the 38 bit $RFREQ$ value with a 10 bit integer portion and a 28 bit fractional portion.

$$RFREQ = (F_{out} \times HS_DIV \times N1) / F_{xtal}$$

For quick calculation in a small microcontroller, the combination of factors HS_DIV , $N1$, and F_{xtal} are scaled, combined and placed in a table indexed by the frequency band number. Now, instead of multiplying F_{out} by $(HS_DIV \times N1) / F_{xtal}$, a table look-up is done and a single division operation is performed in which F_{out} is divided by the reciprocal.

$$RFREQ = F_{out} / (F_{xtal} / (HS_DIV \times N1))$$

This division is a 40 bit by 32 bit operation.

(Note: Typical 32 bit by 32 bit integer division routines result in an integer with the remainder truncated but this division routine performs additional cycles through the division mechanism in order to calculate and retain the fractional portion also.)

Sample calculation:

$$F_{out} = 14,025,000 \text{ (D60128 Hex)}$$

$$F_{xtal} = 114,285,000 \text{ (6CFD9C8 Hex)}$$

$$HS_DIV = 11 \text{ (D Hex)}$$

$$N1 = 34 \text{ (22 Hex)}$$

$$RFREQ \text{ (scaled by } 2^{28}) =$$

$$2DE5A8555 \text{ (Hex)}$$

The $RFREQ$ value is scaled by 2^{28} . The integer portion is 2D (Hex) and the fractional portion is E5A8555 (Hex). The $RFREQ$ value is scaled in this manner so that it is ready to be loaded into the Si570 registers as shown in Table 3.

Later, when the HS_DIV and $N1$ values are manipulated into the required form (HS_DIV_Index and $N1 - 1$) and added to the Si570 registers, the result is shown in Table 4.

The Si570 band tables for PEGen570 are described in Table 6. The entries of the table are pre-calculated using the nominal value for the Si570 internal crystal frequency

(114.285 MHz). The table entries, combining the crystal frequency with other parameters needed to generate RF in that frequency range, are stored in the PIC EEPROM and are loaded into the PIC volatile memory at power-up. This nominal frequency is almost never perfect, of course, but the Si570 is calibrated in the factory to use corrected parameter values in order to produce the default start-up output frequency of exactly 10.00 MHz. (Other Si570 part numbers use different start-up frequencies.)

By holding Pushbutton 3 down during power-up, the application is directed to retrieve the parameters from the Si570 non-volatile EEPROM memory. The software then does a "reverse calculation" to find the actual Si570 crystal frequency as determined by the factory to produce 10.00 MHz. After the actual crystal frequency is determined, the table entries are recalculated and copied back to non-volatile EEPROM. When Pushbutton 3 is released, the PIC restarts and populates the tables with the newly calculated values.

The SetupFxtal(•) routine is called at calibration time only. It retrieves the Si570 registers from the part, extracts the HS_DIV , $N1$, and $RFREQ$ values, and uses this formula to find the calibrated crystal frequency as determined during manufacturing. The default frequency for the Si570 being used in this project (570CAC000107DG or 570CBC000107DG) is 10.0 MHz.

Normal frequency formula: $F_{out} = (F_{xtal} \times RFREQ) / (HS_DIV \times N1)$

Rearranged to give: $F_{xtal} = (F_{out} \times HS_DIV \times N1) / RFREQ$

The following steps are taken:

- 1) Extract $HSDIV_Index$ from the Si570 words and convert to HS_DIV .
- 2) Extract $(N1 - 1)$ from the Si570 words and convert to $N1$.
- 3) Extract $RFREQ$ from the Si570 words.
- 4) Multiply HS_DIV by $N1$.
- 5) Divide $RFREQ$ by $(HS_DIV \times N1)$.
- 6) Divide by default F_{out} (10,000,000).

As an example, Table 5 shows values as extracted from one Si570 with a 10 MHz start-up frequency.

The values of the fields of the registrations shown in Table 5 are as follows:

Extracted HS_DIV Index = 2 so HS_DIV is 6.

Extracted $(N1 - 1) = 4F$ (hex) which is 79 (dec) so $N1 = 80$ (dec).

Extracted $RFREQ$ Integer = 2A (hex) or 42 (dec).

Extracted $RFREQ$ Fractional = 050E9FD (hex).

Note that $RFREQ$ is scaled by 2^{28} . The decimal value can be determined by converting the entire $RFREQ$ value to decimal and then dividing by 2^{28} .

$$RFREQ = 2A050E9FD \text{ (hex)} =$$

11,279,591,933 (dec).

$$11,279,591,933 / 2^{28} = 11,279,591,933 / 268,435,456 = 42.0197.$$

The CalDivide routine is used in the SetupFxtal routine. It performs this calculation:

Calculate F_{xtal} with this formula:

$$F_{xtal} = (F_{out} \times HS_DIV \times N1) / RFREQ$$

Form used by routine:

$$F_{xtal} = (F_{out} / RFREQ) \times HS_DIV \times N1$$

This requires a 40 bit by 40 bit division followed by a 32 bit by 8 bit multiplication. To retain important significant figures, F_{xtal} is scaled by multiplying it by 256 before the division, so F_{out} must also be scaled by 256 before performing the calculation.

$$F_{xtal} \times 256 = (10,000,000 \times 256) \times (6 \times 80) / 42.0197$$

$F_{xtal} = 114.231984$ MHz (compare to 114.285 MHz nominal) Note that this F_{xtal} value, extracted from one sample Si570, is only 0.05% from nominal.

This F_{xtal} value, along with corresponding HS_DIV and $N1$ values from the band tables (described later), is then used to recalculate all values in the HSN1FX table in EEPROM. This table is copied from EEPROM to working (SRAM) memory at power-up so calibrated values will be used for all subsequent $RFREQ$ calculations.

Si570 Bands

The PEGen570 software is implemented with 24 frequency bands. (Note that these do not correspond to amateur bands.) Most of the parameters that the Si570 requires to produce the desired output RF signal are in tables in program memory. These program memory tables cannot be modified with program instructions. These tables are used by the application by using the band number as an index.

One table is located in the PIC data memory, and can be modified. This table is populated by extracting values from EEPROM upon power-up. This table consists of 24 entries, each entry containing a starting frequency requiring 4 bytes. This means that the 24 band table requires 96 bytes of memory. Since the maximum size of any single bank of data memory in the 16F88 (or any "16F" PIC for that matter) is 96 bytes, this determines the maximum number of bands that can easily be handled in the PIC. With additional overhead the size could be expanded and then the upper frequency could be increased. The CMOS version of the Si570, however (the version that the daughtercard is designed to use), has a maximum frequency of 160 MHz. This means the current 96 byte table with an upper limit of 157 MHz is reasonable for this Si570 version. The lower limit of the Si570 is 10 MHz and the 96 byte table also handles this limit.

The 24 PEGen570 bands were created by

Table 6
PEgen570 Bands

BAND	Frequency Range						
0	10 - 11 MHz	6	19 - 21 MHz	12	36 - 41 MHz	18	81 - 90 MHz
1	11 - 12 MHz	7	21 - 23 MHz	13	41 - 47 MHz	19	90 - 101 MHz
2	12 - 13 MHz	8	23 - 25 MHz	14	47 - 54 MHz	20	101 - 111 MHz
3	13 - 15 MHz	9	25 - 28 MHz	15	54 - 61 MHz	21	111 - 128 MHz
4	15 - 17 MHz	10	28 - 32 MHz	16	61 - 70 MHz	22	128 - 135 MHz
5	17 - 19 MHz	11	32 - 36 MHz	17	70 - 81 MHz	23	135 - 157 MHz

examining the Si570 spec sheet and making calculations with a spreadsheet based on the Si570 parameter requirements. Without getting into the esoteric requirements of the Si570 frequency generating parameters and the formula involving several specific “multipliers,” the Si570 internal crystal frequency and the desired output frequency, the frequency range of each band was calculated. The table was generated in such a way that the major parameters for each band can be pre-calculated and retrieved from tables when changing frequency. This greatly minimizes the number of complex calculations that must be performed for each frequency change.

The 24 PEgen570 bands are defined in Table 6.

Several tables were constructed, ready for quick access by the frequency update routines. Each table has one entry per band (24 entries).

There is one table in EEPROM with each 4 byte entry containing a combination of HS-DIV, N1 and Fxtal. The table is initially populated with the default crystal frequency (114.285 MHz) but this table is updated during calibration with the actual crystal frequency that is measured and stored in the Si570 during manufacture.

Entries are constructed and scaled in this manner:

$$\text{HSN1FX} = (\text{Fxtal} / (\text{HS_DIV} \times \text{N1})) \times 256$$

At first glance it would appear that one byte is wasted per entry since multiplying by 256 appears to be simply shifting the original number by 1 byte. It is not that simple. The division operation results in a fractional quotient so multiplying by 256 by continuing the division for 8 additional steps preserves important significant figures of the fractional remainder. Subsequent calculations compensate for this scaling factor.

Example: The entry for Band 0 (covering 10 - 11 MHz) is:

$$\text{HSN1FX0} = (114,231,984) / (46 \times 11) \times 256 = 57,793,256 \text{ (dec)} = 371\text{DAE8} \text{ (hex)}$$

Note that with the nominal crystal frequency the default entry would have been:

$$\text{HSN1FX0} = (114,285,000) / (46 \times 11) \times 256 = 57,820,079 \text{ (dec)} = 37243\text{AF} \text{ (hex)}$$

There is one table in volatile memory (SRAM). This table is identical to the



Figure 13 — The first line of the LCD shows RFREQ.

HSN1FX table in EEPROM. Accessing EEPROM during program execution is relatively slow so this 24 entry table is copied from EEPROM to fast-access program memory at power-up time (4 bytes per entry).

These tables have one entry per band in program (FLASH) memory.

1) SiBandTable — A table containing the lower limits (in MHz) of the frequencies for each band (4 bytes per entry).

2) BandN1Minus1 — A table containing the selected N1 value for each band (1 byte per entry).

3) BandHSDIVIndex — The selected HSDIV Index for each band (1 byte per entry).

4) BandHSNID2 — The selected values of HSDIV and N1 multiplied together and divided by 2 (1 byte per entry). No significant figures are lost in dividing the HS_DIV and N1 product by 2 since each selected N1 is an even number.

User Interface

The user interface for the PEgen570 application is very simple. It uses two pushbuttons, an encoder, and a 2-line by 16-character LCD. A simple menu for changing configuration is activated via the two pushbuttons.

The “Reset” pushbutton on the PIC-EL board is configured (via the CONFIG statement in the source code) such that it does not perform a microprocessor reset when pressed but to operate as a normal I/O pin instead. This made the pushbutton available for operation and it is needed. To clarify this change in usage, the pushbutton will be referred to as Pushbutton 4 rather than

the Reset pushbutton. This means that the PIC-EL board must be powered down and up after loading new software into the PIC before the new program will start executing. Simply moving the slide switch from PGM position to RUN position does not start the PEgen570 program.

Pushbutton 3 and Pushbutton 4 are the two operational pushbuttons. When running the Si570, each time Pushbutton 3 is pressed and released, the tuning digit that is currently being modified by turning the encoder is increased by one digit. It can be advanced up to the 1 MHz position. Similarly, each time Pushbutton 4 is pressed and released, the tuning digit that is currently being modified by turning the encoder is decreased by one digit. The digit that is currently being modified by the encoder is underlined.

When the program is running, pressing and holding Pushbutton 3 for longer than 2 seconds stores the current frequency in EEPROM. This frequency is used as the start-up frequency on subsequent power-ups.

Menu

A simple menu is used for changing mode between upper and lower sideband (USB, LSB, CW+ or CW-). Then the user can turn FSK on or off.

The menu is activated by holding Pushbutton 4 while pushing Pushbutton 3 and then releasing them both. The current mode is shown in character position 1 of line 1 of the LCD. Now, tapping Pushbutton 3 allows the user to toggle through the four sideband options, with the display showing U, L, + or -. Tapping Pushbutton 4 leaves this portion of the menu. Then FSK mode may be

enabled. The current FSK state is displayed (either F or blank) in character position 1 of line 1 of the LCD. Tapping Pushbutton 3 toggles FSK mode between on and off. Tapping Pushbutton 4 once again exits the menu.

Sideband Select Relay

An external latching relay is engaged or disengaged as the sideband is changed in the menu. PIC output ports RA6 and RA7 attach to HDR6 and HDR5 (pins 15 and 16) respectively. As the sideband is changed in the menu, either RA6 or RA7 is driven high with an 8 ms pulse (with the opposite side being held low) to engage or disengage the external latching relay. The recommended latching relay (TQ2-L-5V — DigiKey part 255-1004-5-ND) requires 14 mA at 5 V for 3 ms plus contact bounce time. The latching relay is intended to enable the proper I and Q phases of the transmitter and/or receiver to set the correct sideband.

Sidetone During Receive (or FSK Shift)

Header HDR7, attached to PIC input port RB7, is monitored by the software to deter-

mine whether or not to shift the frequency by the sidetone amount if FSK is not active, or to shift the frequency by the FSK shift size if FSK is active. In CW+ or CW- mode, HDR7 is expected to be set to a low state by exter-

nal transmit/receive circuitry during receive operations and to a high state during transmit operations. The software continually monitors the signal at HDR7 and, when it is detected to be low while in CW- mode, shifts

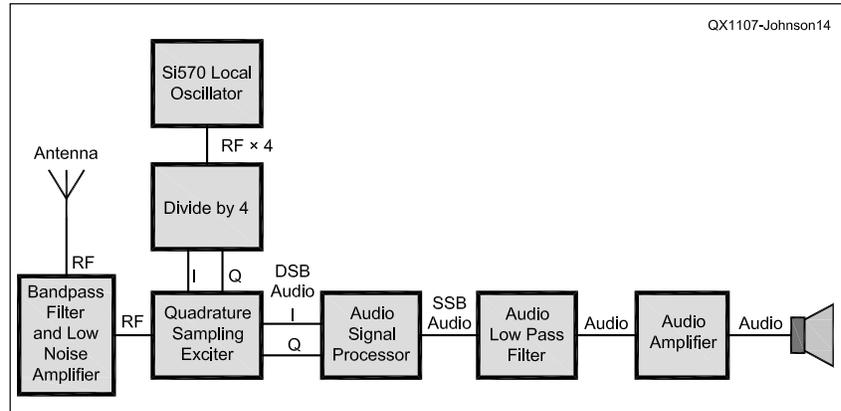
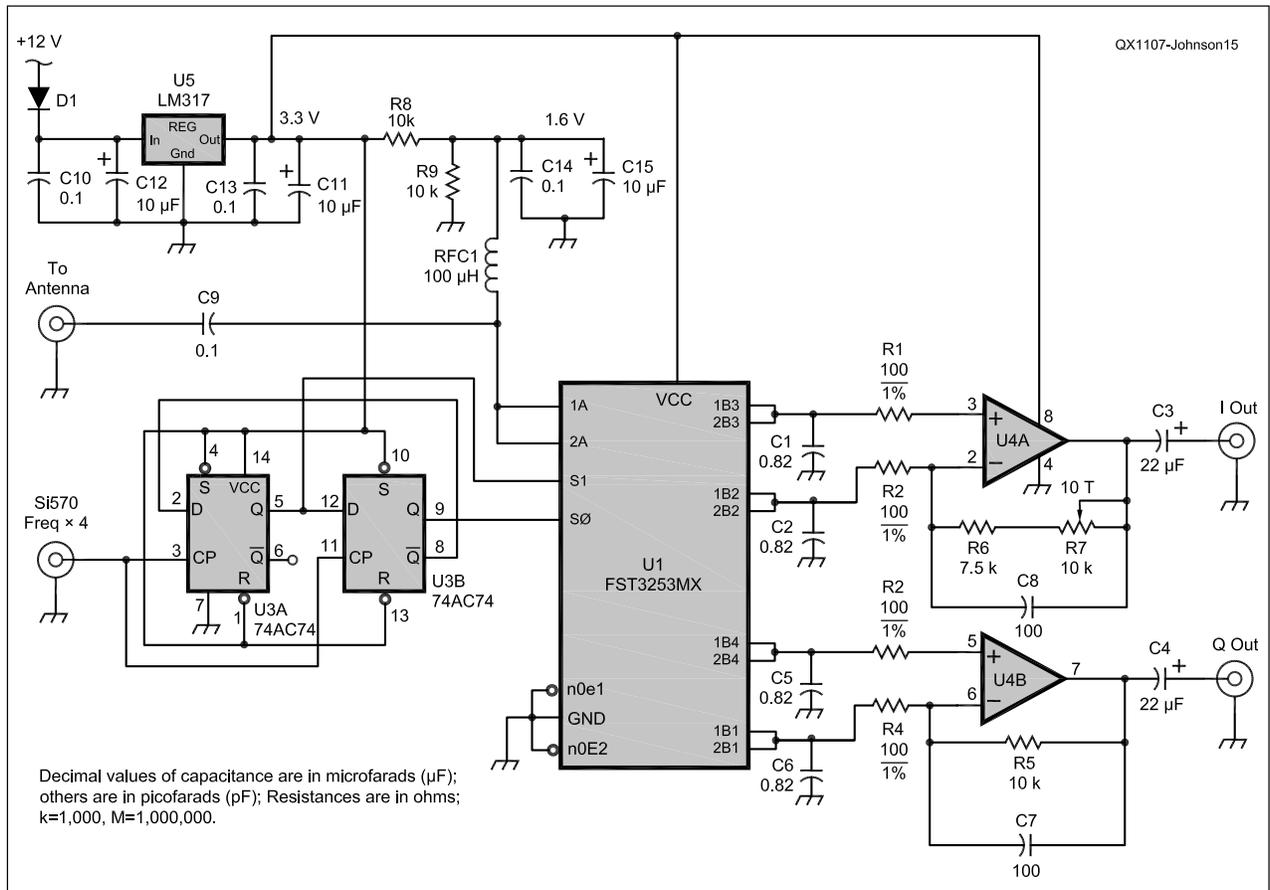


Figure 14 — This block diagram represents a CW or SSB Receiver.



Decimal values of capacitance are in microfarads (µF); others are in picofarads (pF); Resistances are in ohms; k=1,000, M=1,000,000.

Figure 15 — Here is the schematic diagram of a receiver using the Si570 P-PLL and a PC for audio processing.

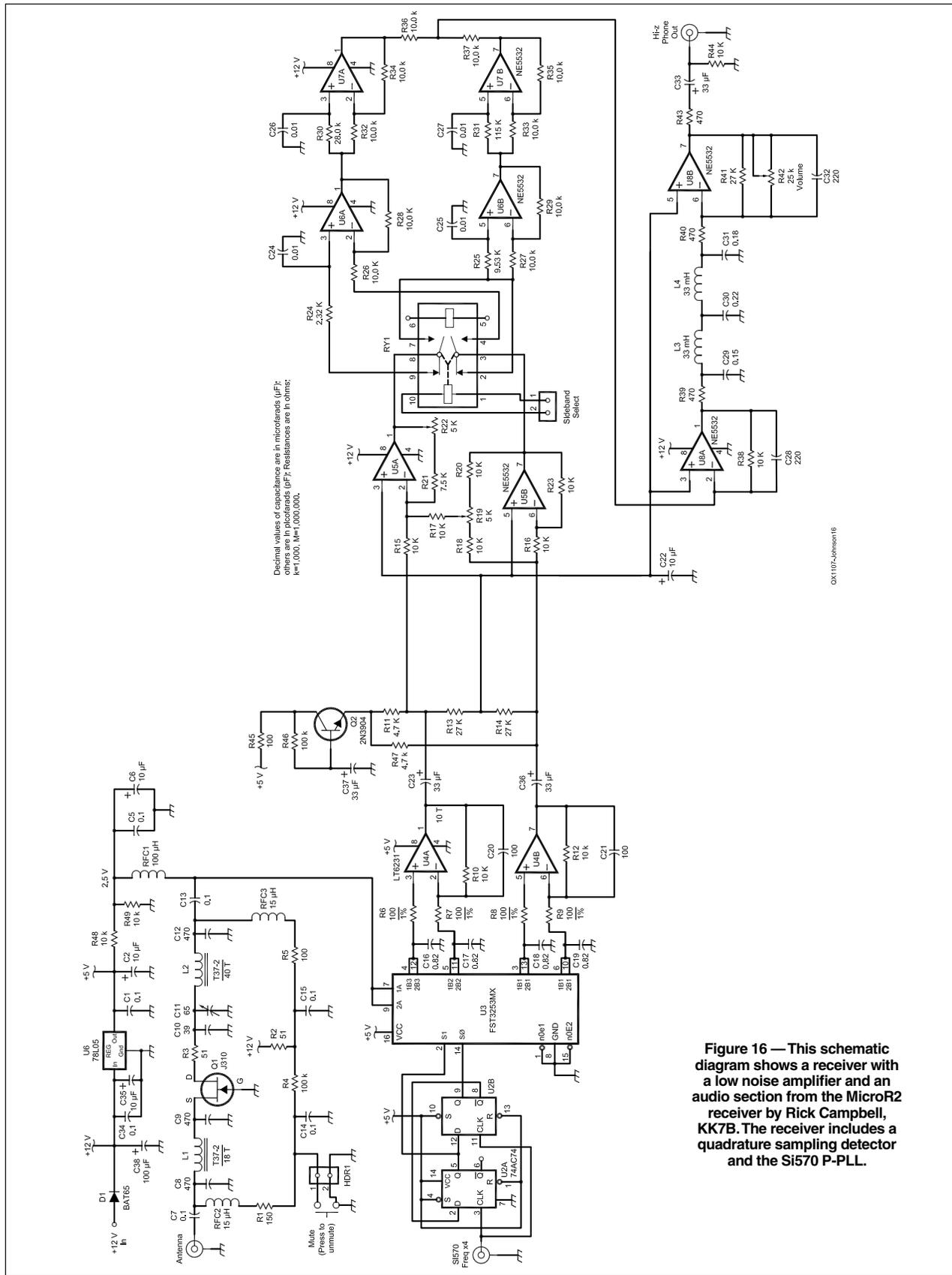


Figure 16 — This schematic diagram shows a receiver with a low noise amplifier and an audio section from the MicroR2 receiver by Rick Campbell, KK7B. The receiver includes a quadrature sampling detector and the Si570 P-PLL.

the frequency down by 600 Hz from the nominal, displayed frequency. If the mode is CW+ and HDR7 is set LOW (receive), the frequency is shifted up by 600 Hz from the nominal, displayed frequency. In either case, whenever HDR7 is detected to be HIGH, indicating Transmit operation, the frequency will be set back to the nominal frequency that is displayed on the LCD.

When FSK mode is activated via the menu, the frequency is set to the displayed frequency when the signal on HDR7 is HIGH (the MARK frequency) and is shifted down by 170 Hz when the signal on HDR7 is LOW (the SPACE frequency).

How fast does it switch? The software looks at the signal on HDR7 often enough

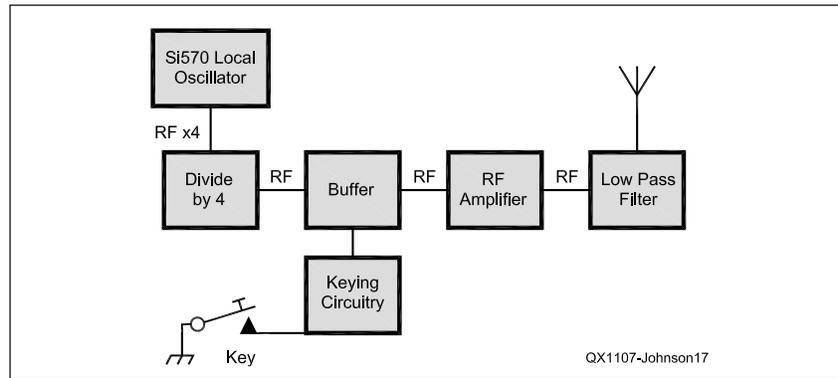


Figure 17 — A 40 m CW Transmitter is shown in this block diagram.

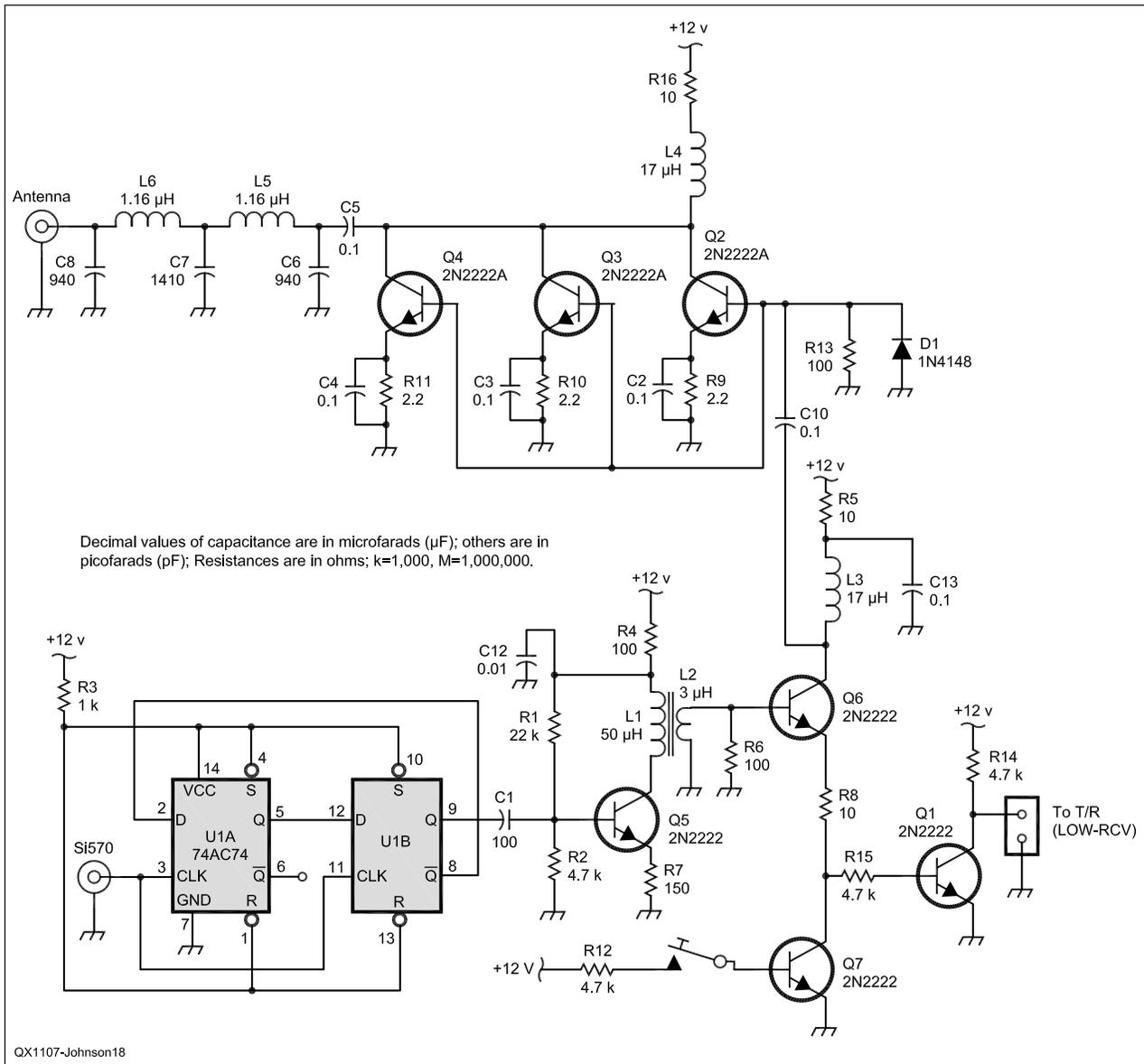


Figure 18 — This schematic diagram shows a 40 m CW Transmitter that uses the Si570 P-PLL as the local oscillator.

to detect and change the frequency within 1.6 ms of HDR changing state. That's fast enough for QSK.

Liquid Crystal Display

The first line of the LCD shows the current frequency. The second line is for debug purposes and when debug mode is enabled, shows the hex digits for the six Si570 frequency-specifying registers (SiReg7 through SiReg12) starting at LCD position 1. The current band number is displayed in positions 15 and 16 of line 2.

The PEgen570 application can be configured to display the Si570 frequency or it can be configured to display the Si570 frequency divided by two or four. The divide-by-four option is useful when the signal generator is being used as a signal source for a QSD/QSE ("Tayloe") mixer. The circuitry for these mixers usually divides the input frequency by four so this software option allows the LCD to display the mixer's operating frequency.

FSK Operation

PEgen570 has the capability of running in FSK mode as well. When FSK mode is enabled in the software, header HDR7 on the Control Board is used for FSK modulation. When HDR7 is modulated (header pins "opened" or "shorted" by external hardware circuitry) the frequency is shifted from MARK (nominal frequency) to SPACE (170 Hz below nominal displayed frequency). When HDR7 is set high (not shorted to ground) the software will command the Si570 to generate RF at the MARK frequency and when HDR7 is set low (shorted to ground) the software will command the Si570 to generate RF at the SPACE frequency.

If the user is not interested in FSK operation, header HDR7 is available for re-commissioning.

Debug Mode

If debug mode is turned on (by pressing and holding PB3 and PB4 during power-up), the Si570 registers and the current Si570 band number are displayed on the second line of the LCD, as shown in Figure 13.

Ideas for Future Modification

The source code of this software is available for download from the ARRL QEX website, for experimenters to examine, change and extend to accommodate personal preferences.⁴ A couple of items are easy to imagine:

1) Make the CW sidetone frequency changeable. Currently the sidetone frequency is fixed at 600 Hz. (600 Hz is added to or subtracted from the base frequency during receive operation and the base frequency is restored during transmit operation.)

2) Display additional information on the LCD: receive versus transmit, sidetone and so on.

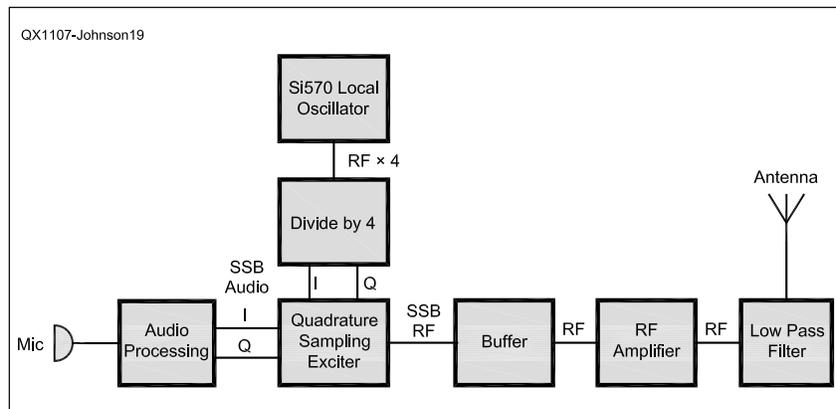


Figure 19 — Here is a block diagram of a 40 m SSB Transmitter that uses the Si570 P-PLL as the local oscillator.

3) Startup frequency is now saved in EEPROM. Add code to save other current settings.

4) Personalize line 2 of the display with the operator's call sign.

Example Receivers and Transmitters Using the Si570 Programmable PLL

Figure 14 shows a block diagram and Figure 15 is a schematic diagram for a receiver that uses the Si570 P-PLL and a QSD to produce I and Q audio signals for processing in a PC with software such as the Rocky SDR software for the SoftRock radio.^{5,6}

Figure 16 shows the schematic of the Si570 LO and a QSD combined with a MicroR2 low noise amplifier and audio processing section designed by Rick Campbell, KK7B.⁷ (Also see Note 1.)

Figure 17 is a block diagram showing the Si570 LO and a QSD in a 40 m CW transmitter. (See Note 1.) Figure 18 is the corresponding schematic diagram. Figure 19 is a block diagram of a 40 m SSB transmitter using the Si570 programmable PLL.

Conclusion

The Si570 programmable PLL from Silicon Labs opens up a myriad of new possibilities for Amateur Radio experimenters to explore. I hope this article has given you some ideas. To continue the discussion, please join us on the PPLL-VFO YAHOO group (www.groups.yahoo.com/group/ppll-vfo). Kits are available from Bill Kelsey, N8ET, at Kanga US; web page (www.kangaus.com) or e-mail him at kanga@kangaus.com. For questions, comments, source code and schematics see the YAHOO group or my web page, www.cbjohn.com/aa0zz, or contact me at aa0zz@arrrl.net. Happy experimenting!

Craig Johnson, AA0ZZ, lives in St. Paul Minnesota. He has a Bachelor's degree in Electrical Engineering and a Masters degree in Business Administration. He worked for Unisys for 35 years on the design and development of large computers, and then switched to working with microprocessors — hardware as well as software — in the development of medical devices and "smart" weapons for the military.

Craig earned his first Amateur Radio license in 1964, at the age of 14. He credits ham radio with sparking his interest in electronics, and pointing him toward a career in electrical engineering. For several years Craig led a team of Volunteer Examiners and helped hundreds of people in the St. Paul area earn or upgrade their licenses. He still serves as a VE on occasion. He is an active member of the Minnesota QRP Society and QRP ARCI.

Craig is married and has three children. All five members of his family are licensed Amateurs. Craig enjoys CW, operating QRP, DXing and contesting. He is happiest, however, when he is tinkering, building or experimenting with new designs, circuits and software. His current interests are centered around projects that use micro-controllers, direct digital synthesis and digital modes. He holds seven US Patents for his work in computer hardware and software.

Notes

¹Gerald Youngblood, AC5OG, "A Software-Defined Radio for the Masses, Part 1", QEX, Jul/Aug 2002, pp 18-20.

²Craig Johnson, AA0ZZ, "Learning to PIC with a PIC-EL — Parts 1 and 2," QST, May 2007 and June 2007 and "Pickle with a USB Interface," QST, Feb 2010.

³Craig Johnson, AA0ZZ, "The IQPro: A High Performance Quadrature DDS VFO" QEX, May/June 2006, pp 8-22.

⁴The author's program source code is available for download from the ARRL QEX website. Go to www.arrrl.org/qexfiles and look for the file 7x11_Johnson.zip.

⁵Alex Shovkoplyas, VE3NEA; www.dxatlas.com/Rocky/

⁶Tony Parks, KB9YIG; www.kb9yig.com/

⁷Rick Campbell, KK7B, "The MicroR2 — an Easy to Build 'Single Signal' SSB or CW Receiver", QST, Oct 2006.

